

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	822	(semiconductor near element) near9 crack	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 13:11
L2	304	(semiconductor near element) near9 crack same resin	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 13:11
L3	20	(semiconductor near element) near9 crack same resin and rigid \$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 13:11
S1	0	("6064114" "6617655" "6797544").PN. and (semiconductor or wafer or substrate) and terminal and plate and (resin near binder) and rigidity and bump and wir\$4 and electrode and "CMP" and (cut\$4 or dic\$4) and (heat\$4 or anneal\$4 or thermal \$4) and mount	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/06 12:10
S2	0	(semiconductor or wafer or substrate) and terminal and plate and (resin near binder) and rigidity and bump and wir\$4 and electrode and "CMP" and (cut\$4 or dic\$4) and (heat\$4 or anneal\$4 or thermal \$4) and mount	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/06 12:11

S3	0	(semiconductor or wafer or substrate) and terminal and plate and (resin near binder) and rigidity and bump and wir\$4 and electrode and "CMP" and (cut\$4 or dic\$4) and (heat\$4 or anneal\$4 or thermal \$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/20 14:26
S4	0	(semiconductor or wafer or substrate) and terminal and plate and (resin near binder) and rigidity and bump and wir\$4 and electrode and "CMP" and (cut\$4 or dic\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/06 12:12
S5	0	(semiconductor or wafer or substrate) and terminal and plate and (resin near binder) and rigidity and bump and wir\$4 and electrode and "CMP"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/06 12:13
S6	9	(semiconductor or wafer or substrate) and terminal and plate and (resin near binder) and rigidity and bump and wir\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/06 12:13
S7	9	(semiconductor or wafer or substrate) and terminal and plate and (resin near binder) and rigidity and bump and wir\$4 and electrode	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/06 12:13

S8	1	(semiconductor or wafer or substrate) and plate and (resin near4 binder) and bump and wir\$4 and electrode and terminal and "CMP" and ((cut\$4 or dic\$4) near8 plate) and viscosity and liquid and (heat\$4 or thermal\$4 or anneal \$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/20 14:36
S9	1	(semiconductor or wafer or substrate) and plate and (resin near4 binder) and bump and wir\$4 and electrode and terminal and "CMP" and (cut\$4 or dic\$4) and viscosity and liquid and (heat\$4 or thermal\$4 or anneal \$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/20 14:37
S10	2	(semiconductor or wafer or substrate) and plate and (resin near4 binder) and bump and wir\$4 and electrode and terminal and "CMP" and (cut\$4 or dic\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/20 14:38
S11	10	(semiconductor or wafer or substrate) and plate and (resin near4 binder) and wir \$4 and electrode and terminal and "CMP" and (cut\$4 or dic\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/20 14:41
S12	39	(semiconductor or wafer or substrate) and plate and (resin near4 binder) and "CMP" and (cut\$4 or dic\$4) and rigidity	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/17 08:41
S13	50091	wiring near4 electrode	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 09:08

S14	2496	(wiring near4 electrode) and rigid\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 09:13
S15	1761	(wiring near4 electrode) and rigid\$4 and plate	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 09:14
S16	60	(wiring near4 electrode) and rigid\$4 and plate and (resin near4 binder)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 09:14
S17	36	(wiring near4 electrode) and rigid\$4 and plate and (resin near4 binder) and terminal	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 09:14
S18	9	(wiring near4 electrode) and rigid\$4 and plate and (resin near4 binder) and terminal and (semiconductor near4 element)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 09:15
S19	9	(semiconductor near9 plate) and (resin near4 binder) and bump and (wir\$4 near9 layer) and ((cut \$4 or dic\$4) near9 plate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/04 13:02
S20	6	(semiconductor near9 plate) and (resin near4 binder) and bump and (wir\$4 near9 layer) and ((cut \$4 or dic\$4) near9 plate) and align\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/04 13:07
S21	109170	(semiconductor near element)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/04 13:08

S22	17506	(semiconductor near element) near9 surface	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/04 13:08
S23	14	(semiconductor near element) near9 surface and plate and (resin near binder) and interpos\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/04 13:09
S24	4	(semiconductor near element) near9 surface and plate and (resin near binder) and interpos\$4 and bump and wir\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/04 13:09
S25	3	semiconductor and plate and (resin near binder) and rigidity and bump and wir\$4 and polish\$4 and (cut \$4 or dic\$4) and viscosity and (liquid near9 resin)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 12:50
S26	241	semiconductor and plate and (resin near binder) and rigidity	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 12:50
S27	13	semiconductor and plate and (resin near binder) and rigidity and bump	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 12:50
S28	110217	(semiconductor near element)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/17 08:50
S29	21912	(semiconductor near element) and plate	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/17 08:50

S30	193	(semiconductor near element) and plate and (resin near binder)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/17 08:50
S31	20	(semiconductor near element) and plate and (resin near binder) and rigid\$4 and wir\$4 and (cut\$4 or dic\$4) and electrode	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/17 10:31
S32	3	(semiconductor near element) and plate and (resin near binder) and rigid\$4 and polish\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/17 10:28
S33	3	(semiconductor near element) and plate and (resin near binder) and rigid\$4 and wir\$4 and (cut\$4 or dic\$4) and electrode and polish \$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/17 10:36
S34	49	semiconductor and plate and (resin near binder) and rigid\$4 and wir\$4 and (cut\$4 or dic\$4) and electrode and polish \$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/17 10:37
S35	49	semiconductor and plate and (resin near binder) and rigid\$4 and wir\$4 and (cut\$4 or dic\$4) and electrode and polish \$4 and electrode	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/17 10:38
S36	49	semiconductor and plate and (resin near binder) and rigid\$4 and wir\$4 and (cut\$4 or dic\$4) and electrode and polish \$4 and electrode and (heat\$4 or thermal)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/17 12:15

S37	23	semiconductor and plate and (resin near binder) and rigid\$4 and wir\$4 and (cut\$4 or dic\$4) and electrode and polish \$4 and electrode and (heat\$4 or thermal) and finish\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/17 12:28
S38	15	(resin near binder) near semiconductor	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/17 12:20
S39	2	(resin near binder) near semiconductor and deform	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/17 12:17
S40	7	semiconductor and plate and (resin near binder) and rigid\$4 and wir\$4 and (cut\$4 or dic\$4) and electrode and polish \$4 and electrode and (heat\$4 or thermal) and finish\$4 and bump	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/17 12:30
S41	28	semiconductor and plate and (resin near binder) and rigid\$4 and wir\$4 and bump and electrode	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/17 12:42
S42	115007	(semiconductor near element)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 08:20
S43	19101	(semiconductor near element) near9 connect\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 08:21

S44	998	(semiconductor near element) near9 electrode and (solder near ball)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 08:27
S45	1462	(semiconductor near element) near9 electrode and (solder near (ball or bump))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 08:28
S46	25	(semiconductor near element) near9 electrode and (solder near (ball or bump)) and (resin near binder)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 08:28
S47	22	(semiconductor near element) near9 electrode and (solder near (ball or bump)) and (resin near binder) and (plate or base)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 08:29
S48	24	(semiconductor near element) near9 electrode and (solder near (ball or bump)) and (resin near binder) and (plate or base or substrate or wafer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 08:29
S49	23	(semiconductor near element) near9 electrode and (solder near (ball or bump)) and (resin near binder) and (plate or base or substrate or wafer) and wir\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 08:48
S50	9	(semiconductor near element) near9 electrode and (solder near (ball or bump)) and (resin near binder) and (plate or base or substrate or wafer) and wir\$4 and rigid\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 09:07

S51	2907	(semiconductor near element) near9 thickness	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 10:27
S52	28	(semiconductor near element) near9 thickness and electrode and resin near binder	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 10:27
S53	24	(semiconductor near element) near9 thickness and electrode and resin near binder and plate	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 10:28
S54	6	(semiconductor near element) near9 thickness and electrode and resin near binder and plate and rigid\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 10:28
S55	6	(semiconductor near element) near9 thickness and resin near binder and plate and rigid\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 10:34
S56	6	(semiconductor near element) near9 thickness and resin near binder and rigid \$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 10:35
S57	247	(semiconductor near element) near9 thickness and rigid\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 10:36
S58	124	(semiconductor near element) near9 thickness and (semiconductor near element) same rigid \$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 10:36

S59	96	(semiconductor near element) near9 thickness and (semiconductor near element) same rigid \$4 and resin	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 10:36
S60	8	(semiconductor near element) near9 thickness and (semiconductor near element) same rigid \$4 and resin and polish\$4 near9 (semiconductor or chip or die)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 11:56

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